

ENCAPSULATED ENERGY-DISSIPATIVE FUSE FOR INTEGRATED CIRCUITS  
AND METHOD OF MAKING THE SAME

ABSTRACT

A laser-programmable fuse structure for an integrated circuit device is disclosed.  
5 In an exemplary embodiment of the invention, the fuse structure includes a conductive layer, the conductive layer completing a conductive path between wiring segments in a wiring layer. An organic material is encapsulated underneath the conductive layer, wherein the fuse structure is blown open by application of a beam of laser energy thereto.